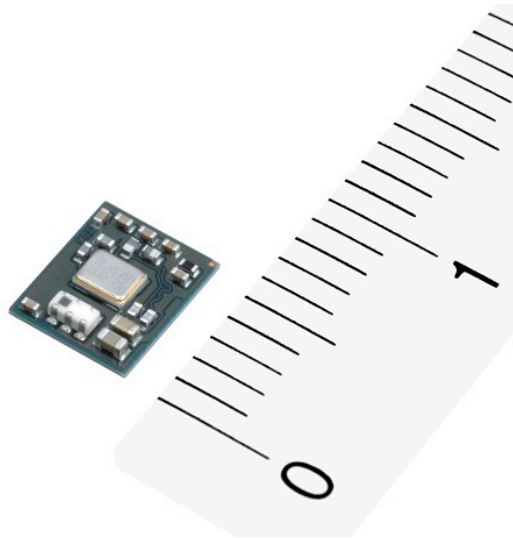


TDK's Ultra-Compact Bluetooth Smart Module

WDD Staff



[TDK](#) [1] (Japan) has presented an ultra compact Bluetooth low energy module designed for the Bluetooth 4.0 low energy (LE) specification, which is being marketed as Bluetooth Smart. The Bluetooth IC die is embedded into the thin substrate, and all the peripheral circuitry, including a quartz resonator, bandpass filter and capacitors, is integrated on top. Its substrate layers route all of the I/Os to a BGA on the module's bottom surface. The new module thus facilitates the hardware design process and allows easy implementation of Bluetooth connectivity simply by connecting it to a power supply and antenna. Additional features include:

- Use in emerging wearable devices.
- A footprint of 4.6 x 5.6 x 1.0 mm.
- A10m communication range.
- A reduced power consumption.

For more information, visit www.tdk.com [1].

Source URL (retrieved on 03/05/2015 - 2:19pm):

<http://www.wirelessdesignmag.com/product-releases/2014/05/tdks-ultra-compact-bluetooth-smart-module>

Links:

[1] <http://www.tdk.com>